Stock Code: **7828**

INNOS
創新服務股份有限公司

Innostar Service Inc.

Pre-Listing Investor Conference

March 25 2026

Lead Underwriter

凱基證券
KGI SECURITIES

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- This presentation contains summaries and assessments of the Company's past, present, and future operations based on information available at the time of preparation. It includes forward-looking statements that are subject to risks, uncertainties, and assumptions, some of which are beyond the Company's control. Actual results may differ materially from those expressed or implied in such statements.
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Risk Factors

- Industry Risks
  1. Exposure to cyclical market fluctuations
- Operational Risks
  1. Customer concentration in probe card equipment
  2. Difficulty in developing experienced technical talent
  3. Finance risks
- Other Material Risks
  - **Please refer to pages 1–7 of the “Risk Factors and Supplementary Disclosures” for further details.**

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Supplementary Disclosures

Pursuant to the requirements set forth in the letter issued by the Taipei Exchange (No. 1150100166) dated January 23, 2026, regarding supplementary disclosures under the Risk Factors section:

For the first three quarters of 2025, revenue and operating profit derived from related party Technoprobe S.p.A. Group (the "TP Group") accounted for 48.31% and 61.05%, respectively, indicating customer concentration. The Company has provided explanations regarding the reasons for such concentration with the TP Group, the cooperation model between both parties, the associated risks, and the corresponding mitigation measures, together with the opinions of the TPEx-recommended securities firms and the certifying CPA.

In recent years, the Company's revenue has been primarily generated from custom-built semiconductor equipment sales. The Company has provided explanations regarding the measures adopted to address risks arising from semiconductor industry cycles and fluctuations in custom-built equipment revenue, together with the opinions of the TPEx-recommended securities firms.

Please refer to pages 8–16 of the "Risk Factors and Supplementary Disclosures" for further details.

Pursuant to the requirements set forth in the letter issued by the Taipei Exchange (No. 1150100166) dated January 23, 2026, regarding supplementary disclosures under the Risk Factors section:

The Company has provided explanations regarding the reasonableness of changes in its business performance and its future development prospects, together with the opinions of the TPEx-recommended securities firms .

The Company's primary products and technologies include MEMS probe card full-line equipment, Cu pillar mass transfer technology, and through-glass via-inserted Cu pillar (TGV-ICP) technology. The Company has provided explanations regarding the technologies and R&D capabilities required for the development of its main products, product application strategies, and its technological differentiation and competitive advantages compared to the market, together with the opinions of the TPEx-recommended securities firms.

Please refer to pages 17–39 of the "Risk Factors and Supplementary Disclosures" for further details.

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Code Stock: **7828**

1.Company Overview & Philosophy

INNOSTAR empowers your manufacturing process and product innovation with expert, end-to-end solutions

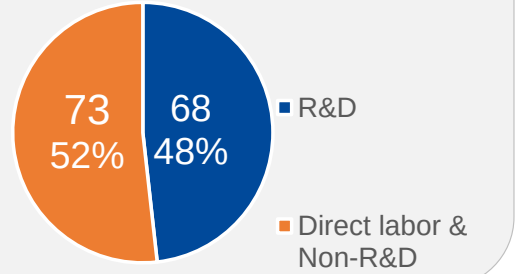
Company Overview

Stock Code: **7828**

創新服務股份有限公司
InnoStar Service, Inc.

- **Established: 2004**
- **Capital:** NTD 367 million
- **Employees:** 141
- **Locations**
  - Hsinchu Plant
  - Taichung Headquarters
  - Kaohsiung Office
- **Core Businesses**
  - Development, manufacturing, and sales of semiconductor automation equipment
  - Advanced packaging solutions
  - Development, manufacturing, and sales of advanced packaging components
  - Probe card repair services and sales of related materials

R&D talent accounts for **48%** of total headcount.





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Key Milestones

2004
- Company established
- Launched first-gen automatic plastic lens-cutting machine
- **Pioneered automation revolution for optical industry**

2014
- **Expanded into advanced semiconductor testing, developed MEMS Probe Card Assembly Equipment for wafer testing**
- **Pioneered automation revolution for probe card industry**

2016
OEM service of MEMS probe assembly for leading foundries, having processed more than 300 million units

2022
Auto Probe Assembly Machine adopted by leading probe card makers

2024
High-density Cu Pillar applied to WIFI modules with substantial sample shipments

Probe Assembly Machine adopted at scale by probe card makers



2025
High-density Cu Pillar applied to power modules, TGV, and PLP modules
- **Technoprobe became strategic investor**
- **Launched comprehensive MEMS probe card automation solutions**



2026
To verify and mass-produce High-density Cu Pillar modules
- **To expand the MEMS probe card equipment lineup**
- **To establish and realize probe card repair capacity**

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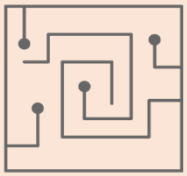
Code Stock: **7828**



2. Industry & Operations Overview

Industry Overview

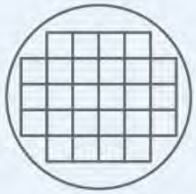
Upstream



IC Design

Foundry

Midstream



IC/Wafer Manufacturing

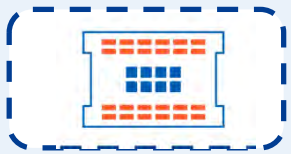
Process & Testing Equipment

Photomask

Chemical



IC Testing (Chip Probing)



Probe Cards for Wafer Testing

Downstream



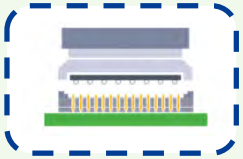
IC Packaging

Process & Testing Equipment

Substrate

Lead Frame

IC Testing



Final Test

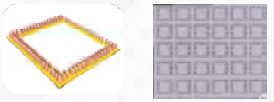
IC Distribution



Probe Assembly and Related Automation Equipment



CoWoS Substrate Component Repair Equipment



High-density Cu Pillar Modules



Pogo Pin Assembly & Related Automation Equipment

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Product Portfolio

Probe Card Full-Line Equipment Automation Solutions

- Laser Drilling Machine
- Guide Plate Inspection and Lamination Machine
- Dual-arm Needle Assembly Machine
- Probe Card Inspection Machine
- Laser Reshaping Machine, Laser Cleaning Machine
- Auto Probe Change Machine
- Probe Binning and Aligning Machine
- CoWoS FT Auto Probe Assembly (90um) and Inspection Machine



MEMS Probe Card Repair Lineup

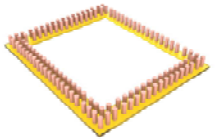
Semiconductor High-Precision Processing

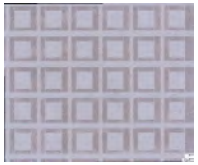
- High-Precision Laser Cutting Machine
- Mini LED Laser Repair Equipment
- Laser De-coating Machinery
- MEMS Mirrors Precision Assembly Machine
- CoWoS Substrate Component Repair Equipment
- High-Precision Spot Welding Machine

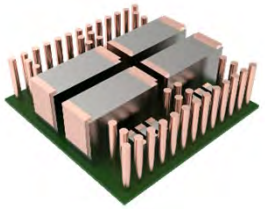


Advanced Packaging

- High-Density Cu Pillar Module for WiFi modules
- High-Density Cu Pillar Module for power modules
- Interposer (10:1) Cu Pillar TGV







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End-to-End Automation Solutions for MEMS Probe Cards

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INNOS End-to-End Probe Card Manufacturing and Repair Equipment

Laser Drilling Machine (LS-11)	Guide Plate Inspection and Lamination Machine (PHIA-02)	Dual-arm Needle Assembly Machine (AT-105)	Probe Card Inspection Machine (PCR-01)	Laser Reshaping Machine (PHR02) & Laser Cleaning Machine (PHC-02)	Auto Probe Change Machine (PIR-02)	Probe Binning and Aligning Machine (PSA-01)
Development completed	Completion expected 1Q26	Development completed	Development completed	Development completed	Development completed	Development completed



Conventional Probe Card Manufacturing Processes

Laser drilling machine	Manual & semi-auto lamination	Manual needle assembly	Manual microscopic inspection	Semi-auto laser cleaning	Manual probe replacement & measurement	Manual binning

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Timeline of MEMS Probe Card Automation/Repair Equipment and Material Kit Sales

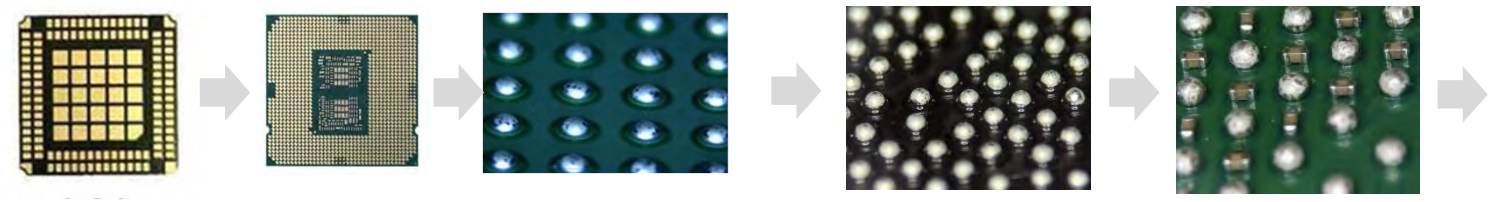
Stock Code: **7828**

#	MEMS probe card-related product	2016-2021	2022 2023	2024	2025 Q1	2025 Q2	2025 Q3	2025 Q4	2026 Q1	2026 Q2	2026 Q3	2026 Q4
1	**Single-arm Needle Assembly Machine**	Needle assembly OEM	Sales start	**Scaled sales**								
2	**Dual-arm Needle Assembly Machine**				Under Development	Under Development	Under Development	**Mass production & shipments**				
3	**Probe Card Inspection Machine**					Under Development	Under Development	**Mass production & shipments**				
4	**Laser Reshaping Machine & Laser Cleaning Machine**					Under Development	Under Development	**Mass production & shipments**				
5	**Auto Probe Change Machine**					Under Development	Under Development	**Mass production & shipments**				
6	**Probe Binning and Aligning Machine**						Under Development	Under Development	**Mass production & shipments**			
7	**Laser Drilling Machine**				Under Development	Under Development	Under Development	Under Development	**Mass production & shipments**			
8	**Guide Plate Inspection and Lamination Machine**					Under Development	Under Development	Under Development	**Mass production & shipments**			
9	**Probe Card Analyzer**							Under Development	Under Development	**Mass production & shipments**		
10	**Probe card repair OEM service**								Production line build	Production line build	**Contract manufacturing**	**Contract manufacturing**
11	**Probe card material kits**					Contract signing/market promotion	Applied to customers' designs	**Limited shipments**	**Sales start**			

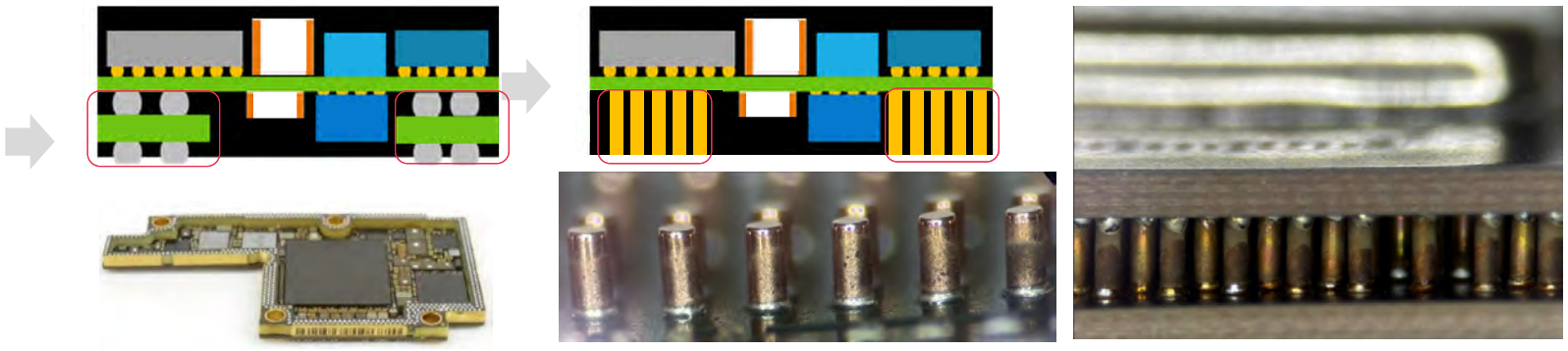
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Advanced Packaging – Advances in Pin-Out Via Technology

Stock Code: **7828**



LGA | LSC (Land side capacitor) | Pre-solder | BGA | BSC (Ball side capacitor)



Frame Board

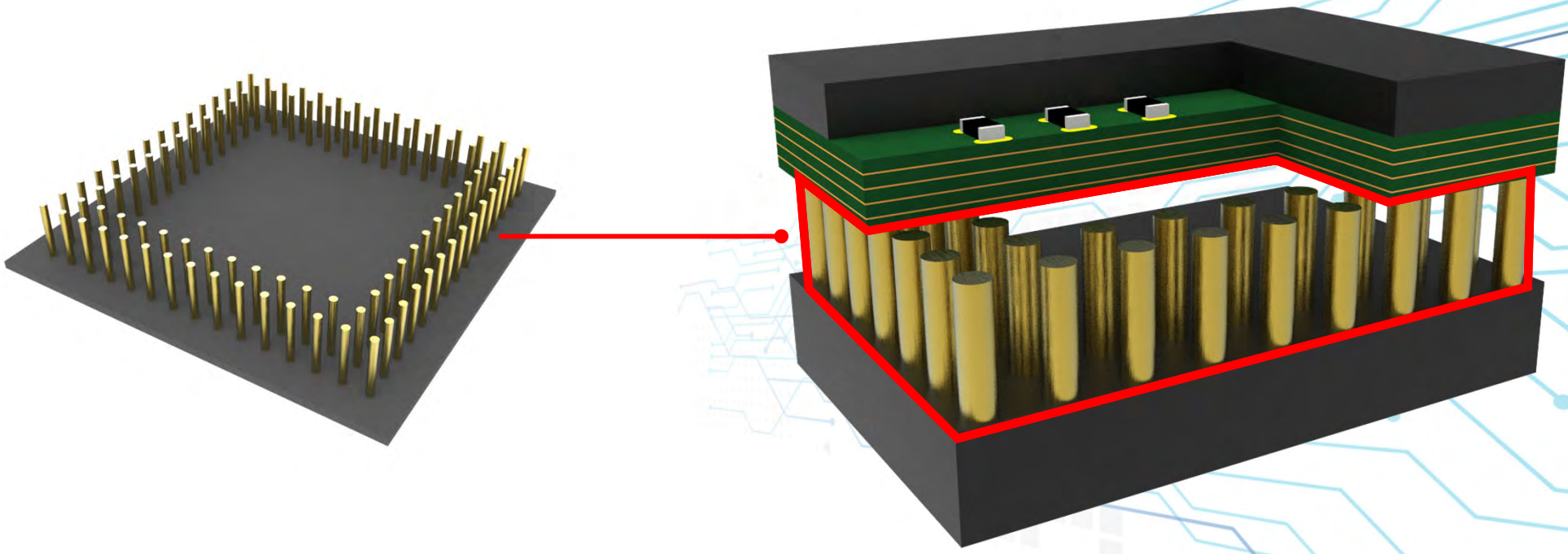
Cu-Pillar

- Fine Pitch
- Higher I/O
- Flexible Design Architecture
- Electrical
- Thermal
- Mechanical

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High-Density Cu Pillar Module

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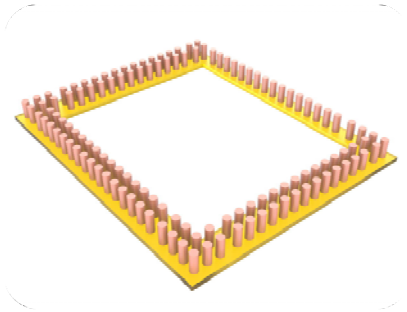


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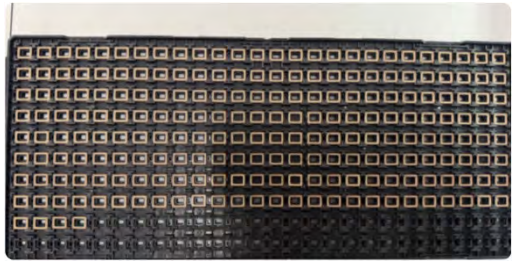
Custom-Built High-Density Cu Pillar Module

Stock Code: **7828**

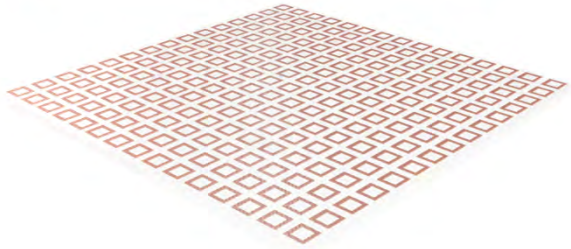
Final product (illustration)



Tray



TGV

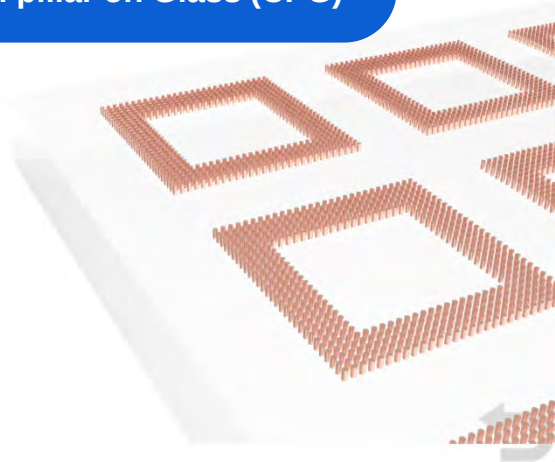


Tape & Reel





Cu pillar on Glass (CPG)

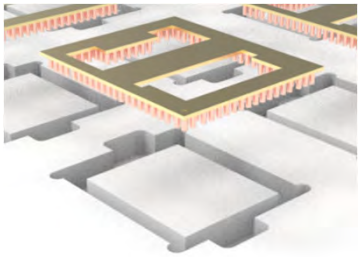


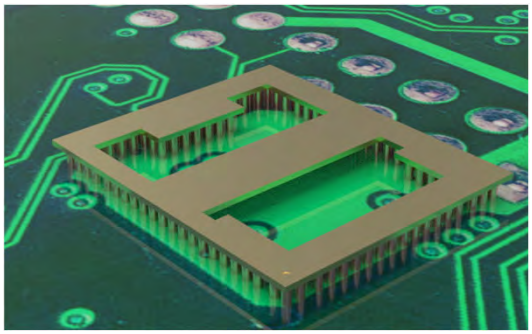
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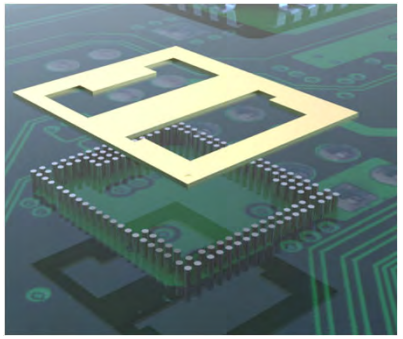
Cu Pillar Modules: Transfer Process

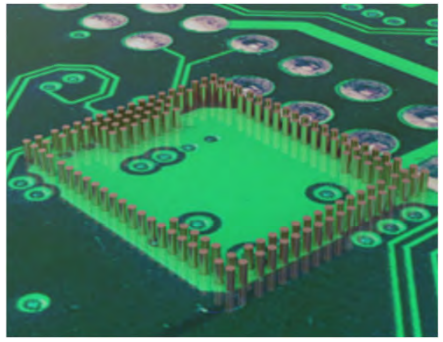
Hydrolyzable module

Pick &Place → Mounted to PCB using nozzle → Reflow → Hot water release at 85°C → Substrate debonding









- Molding Compound



- Submolding or underfill



Non-hydrolyzable module

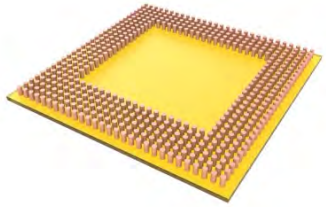
Pick &Place → Mounted to PCB using nozzle → Reflow → Molding Compound → Grinding



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Advanced Packaging: Cu Pillar Modules

Final product (illustration)





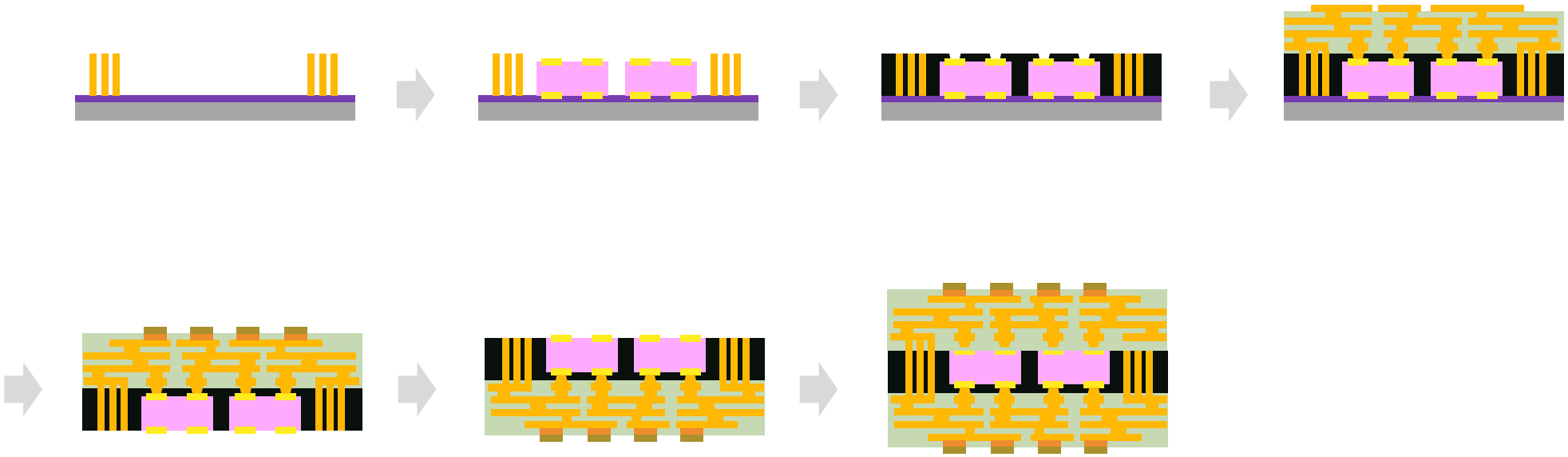


30,000 pins per tray

High-density Cu pillar modules are designed for advanced packaging processes on organic substrates, glass substrates, and wafer-level packaging. They support Cu pillar interconnect applications in high aspect ratio, high conductivity, and high heat dissipation designs, as well as heterogeneous integration and power module packaging.

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Cu pillar on Glass for PLP

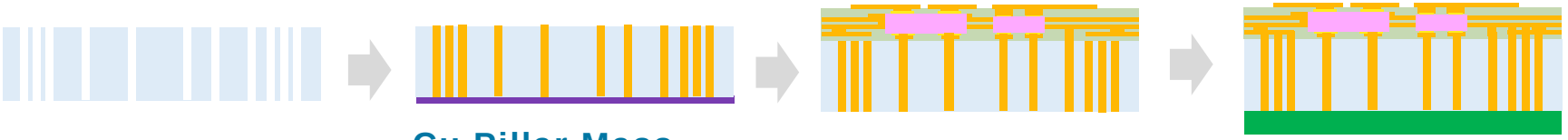


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TGV Interposer 10:1 – RDL Reinforcement

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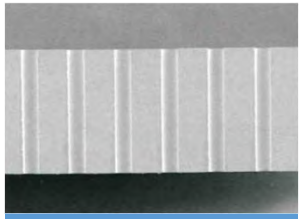
Thermal Shock Validated:
-40 °C ↔ +125 °C (850 Cycles)



Cu Pillar Mass Transfer



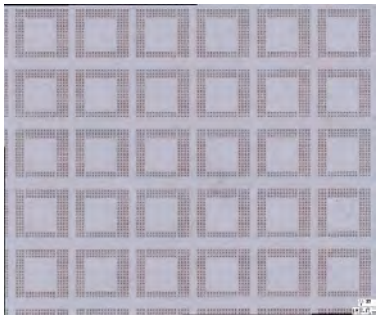
Electroplated Cu pillars <3:1

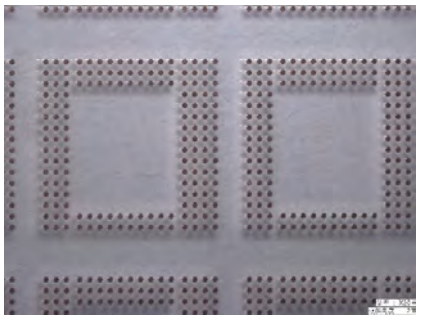


Vertical vias



Smooth side wall





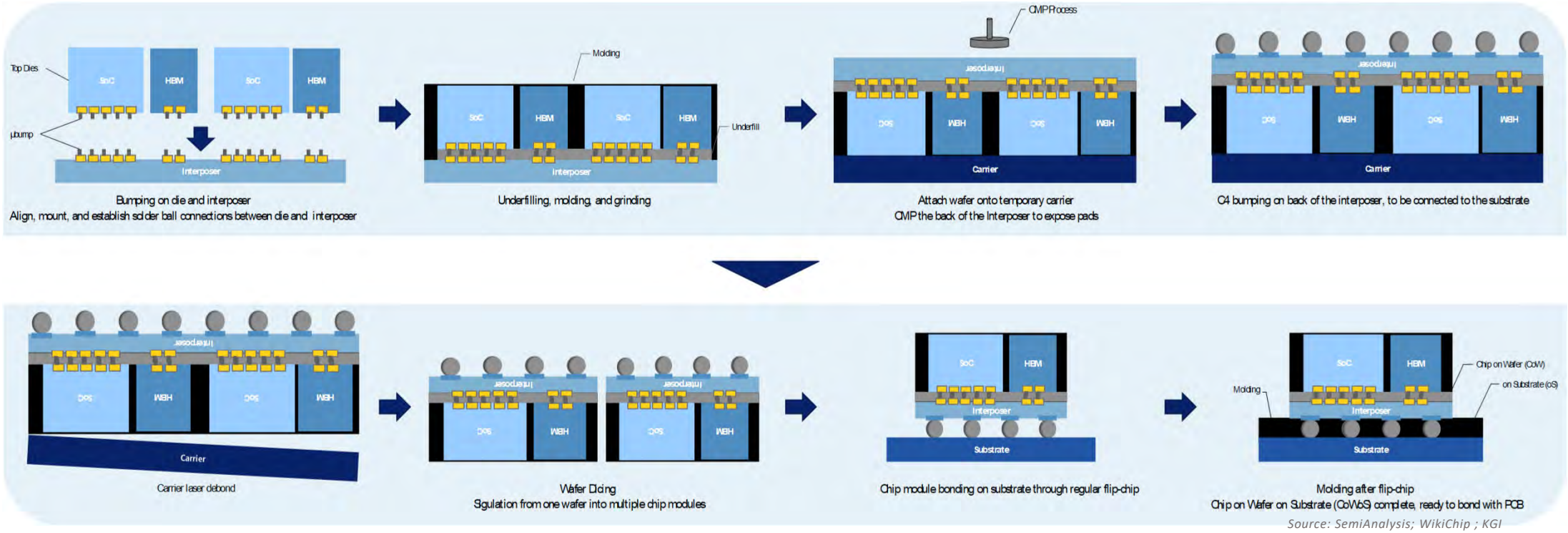


Mass transferred Cu pillars 10:1

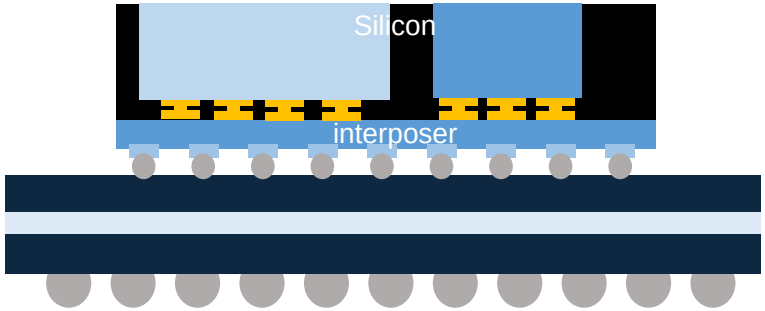
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TGV

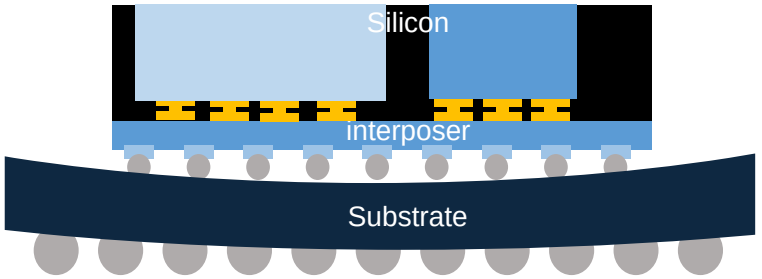
Stock Code: **7828**



Source: SemiAnalysis; WikiChip ; KGI



TGV



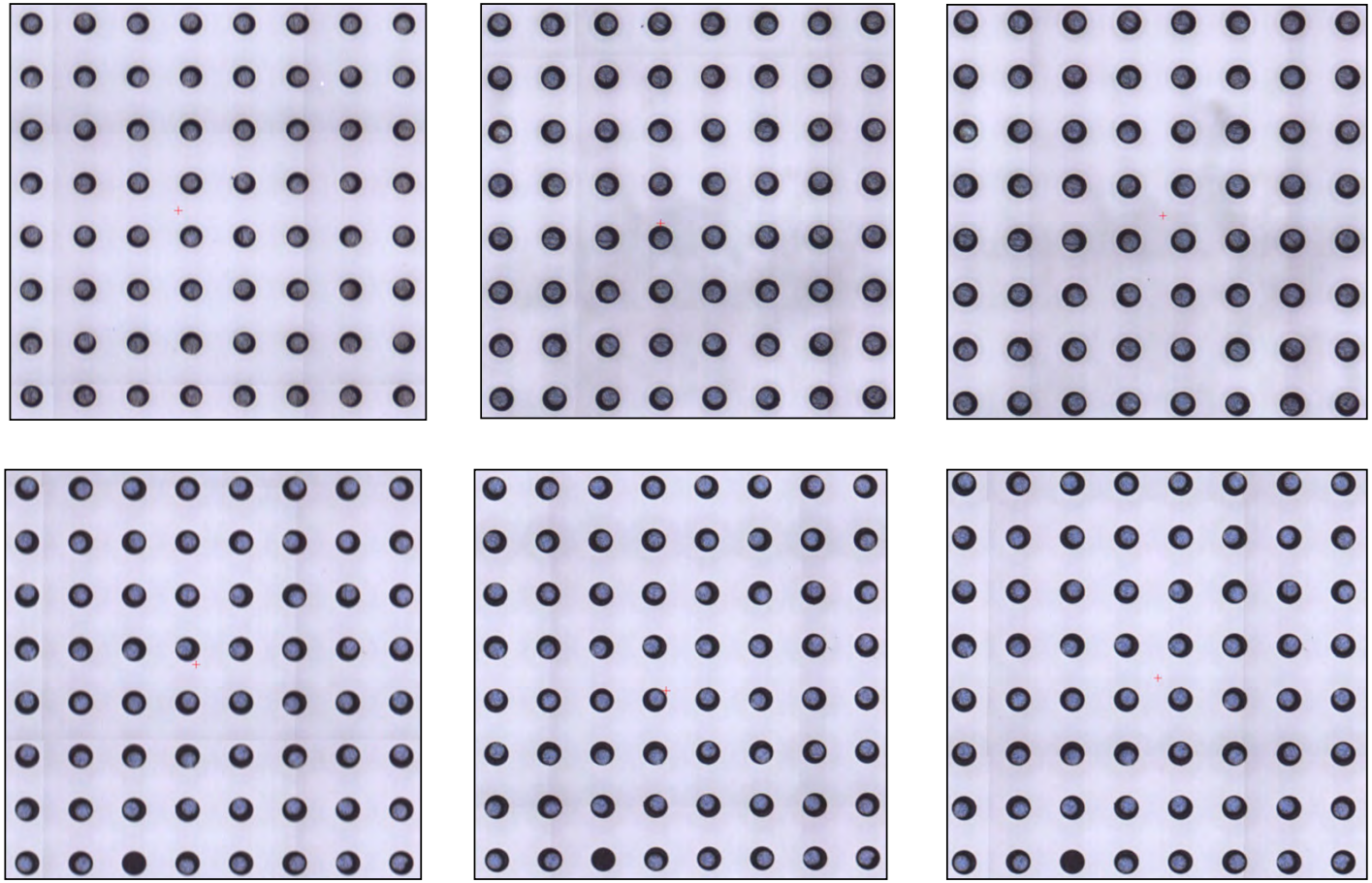
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Thermal Shock Test

Stock Code: **7828**

-40 °C ↔ +125 °C (850 Cycles)

- **Purpose:**
  - Validate TGV reliability under extreme thermal cycling; assess fatigue, cracking, and failure risks from thermal expansion mismatch
- **Conditions:**
  - Standard: JEDEC JESD22-A104F
  - Temperature range
    - Low: -40 °C
    - High: +125 °C
  - Number of cycles: 850
  - Typical transition time: ≤10 min
  - Dwell time at high/low temperatures: 10–15 min
- **Result: PASS**



300 cycles | 620 cycles | 850 cycles

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High-Density Cu Pillar Modules: Adoption Progress

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Customer Segment	Number of Customers	Number of projects	Adoption Progress
TGV high-speed transmission modules 	3	3	• NTI → NPI → **Mass production after 2027**
AI power Modules 	8	11	• NTI → EVT/DVT → PVT → **Adopted for mass production in 2027 (expected)**
RF / Network communication 	5	10	• EVT/DVT → PVT → **Mass production ramp-up since 2026**
VR / AR 	1	2	• NTI / NPI, with mass production planned

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New Facility in Taichung: First-Phase Construction

- First-phase construction to be completed in 1Q26
- Cu Pillar Module line
  - Expand to **4** production lines (expected)
  - Production capacity: **10,000K** pcs/year
- TGV-ICP production line
  - Expand to **12** production lines (expected)
  - Production capacity: **120K** pcs/year

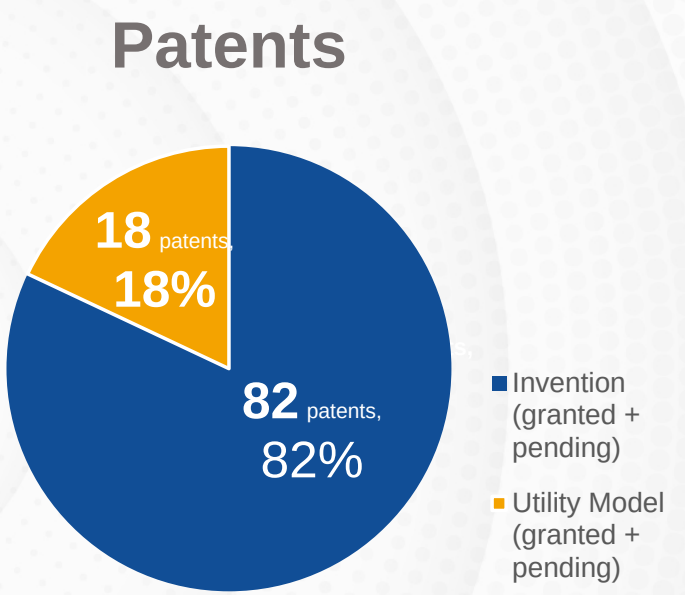


Land acquired on Aug 6, 2025
Land: No. 686, 687, 687-1, Guangming Rd., Dajia Dist., Taichung City
Building: No. 130-1 Xing'an Rd., Dajia Dist., Taichung City
Land area: 3,558.00 km^2
Building area: 3,945.35 km^2
First-phase construction to be completed in 1Q26; second-phase construction to start in 2Q27

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Patents

Patent Category	Granted		Pending	
	Invention	Utility Model	Invention	Utility Model
Semiconductor advanced process equipment	15	1	4	0
Advanced packaging equipment and related products	11	6	26	2
Others	14	8	12	1
Subtotal	40	15	42	3



As of now, Innostar holds 55 patents (40 inventions and 15 utility model patents), with 45 additional applications pending (42 inventions and 3 utility model patents).

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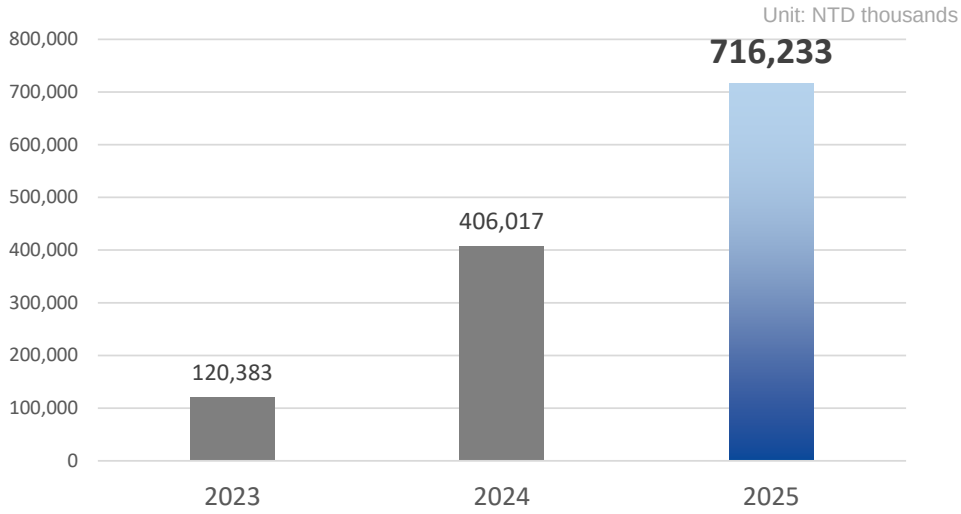
Code Stock: **7828**



3. Performance & Outlook

Operating Performance

Revenue



Financial Results

Unit: NTD thousands; NTD

	2023	2024	2025
Income after tax	(49,934)	149,887	227,671
Gross margin	61.81%	80.26%	76.25%
EPS	(2.33)	5.25	6.33

- Revenue surged 237.27% YoY in 2024, followed by a 76.25% YoY increase in 2025, driven by advances in semiconductor processes and strong AI-driven demand. Innostar also maintained steady growth, supported by consistent shipments of MEMS probe card equipment (Dual-arm Probe Assembly Machine) and full-line automation solutions.

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Outlook: Three Core Pillars for Operational Growth

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Semiconductor Equipment

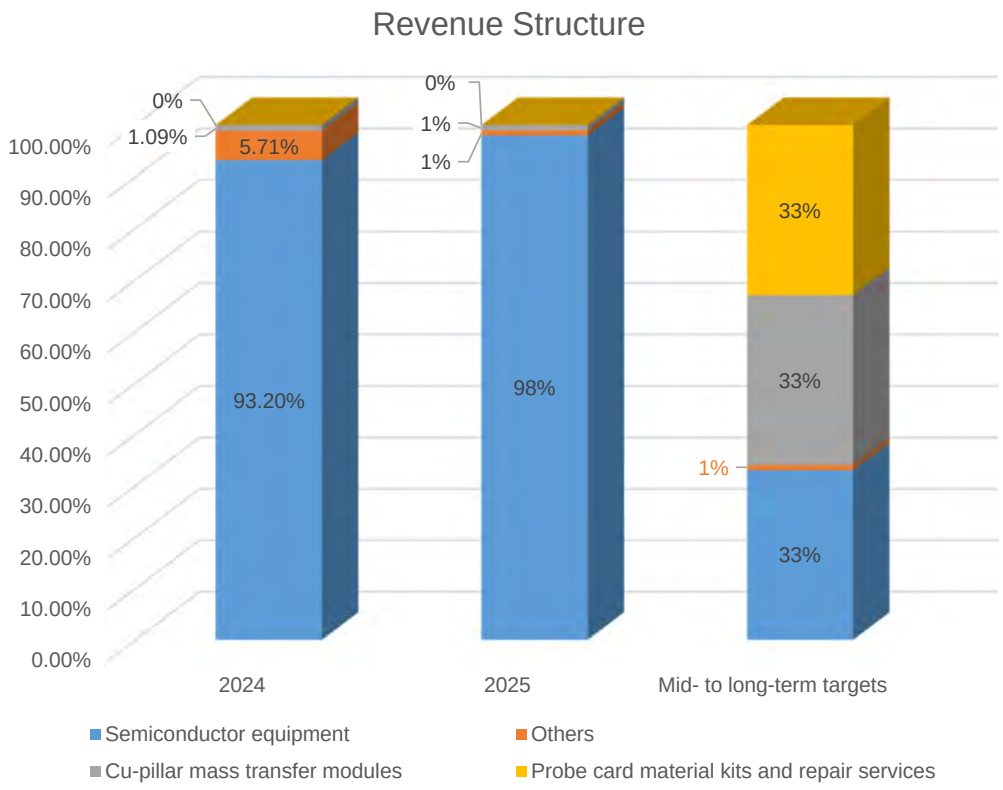
- Advancing automation equipment to meet strong market demand
- Single-arm > Dural-arm probe assembly machines
- Developing probe card repair automation equipment to reduce turnaround time and enhance competitiveness.

Probe Card Material Kits and Repair

- Transitioning into a probe card material kit supplier
- Probe repair services, reducing turnaround time on conventional repair
- Increasing recurring revenue from PC material kit supply and repair services.

Cu Pillar Mass Transfer Modules

- Focusing on power module and TGV CoWoS packaging market
- Mass adoption in 2026 across RF/network communication and high-speed TGV transmission modules.
- Mass adoption in 2027 for AI power modules.



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4. ESG Advancement

ESG Advancement

In 2025, the Sustainability Committee was established to advance ESG governance.

A carbon inventory will begin after the new plant starts operations, with the first ESG report expected by mid-2026.



Environmental Protection

- Zoned air-conditioning and ventilation management
- Waste sorting and recycling
- Energy-efficient lighting
- Rainwater harvesting and reuse
- Solar power planned for the new plant



Social Responsibility

- Performance-based pay
- Employee group insurance and health checkups
- Regular safety and health training, on-site health services, workplace monitoring
- Local hiring prioritized



Corporate Governance

- Board operations and independence
  - Independent directors: > 1/3 of the board
  - Gender diversity on the board
  - Balanced shareholder structure; comprehensive director development
- Integrity and information disclosure
  - Ethical management in practice
  - Financial, operational, and related information disclosed on the company website

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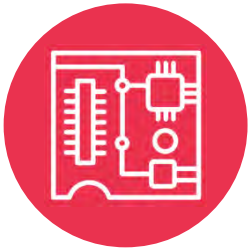
Sustainability and Carbon-Reduction Benefits for Customers

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Probe Card Full-Line Automation Solutions

- **Reduced material waste:** high-precision probe assembly and stable process control minimize probe scrap and rework.
- **Improved energy efficiency:** streamlined manufacturing shortens process time and lowers energy per unit.
- **Enhanced ergonomics:** automation replaces repetitive, high-load manual tasks, reducing health risks for operators



TGV and Cu-Pillar Modules Replacing Conventional Electroplating

- Eliminates the significant power, water, and time demands of conventional plating.
- Minimizes heavy metal pollution and the need for chemical and liquid waste treatment.

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THANK YOU For Your Attention

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